

Ferrite Chip Beads

For power line

ACC (STD) series

Type: HFxxACC2012 [0805 inch]*
 HFxxACC3216 [1206 inch]
 HFxxACC3225 [1210 inch]
 HFxxACC4532 [1812 inch]
 HFxxACC5750 [2220 inch]
 HFxxACC6350

* Dimensions Code JIS[EIA]

Issue date: December 2010

Chip Beads(SMD) For Power Line

Conformity to RoHS Directive

HF70ACC, HF50ACC, HF30ACC Series

FEATURES

- With 4 types rated at 1.5A and 3 types rated at 3A, and with a range of frequency characteristics available for each type, the ACC series facilitates selection of the most appropriate part for any given application.
- Effective EMC suppression over a broad band can be achieved simply by inserting this product into the DC power line on the circuit board.
- Available reflow soldering.
- It is a product conforming to RoHS directive.

PRODUCT IDENTIFICATION

HF70 ACC 201209 - T
(1) (2) (3) (4)

(1) Material name

(2) Series name

(3) Dimension code

(4) Packaging style

T: \varnothing 180mm reel taping

TL: \varnothing 330mm reel taping

TEMPERATURE RANGES

Operating	-40 to +125°C
Storage	-40 to +125°C

PACKAGING STYLE AND QUANTITIES

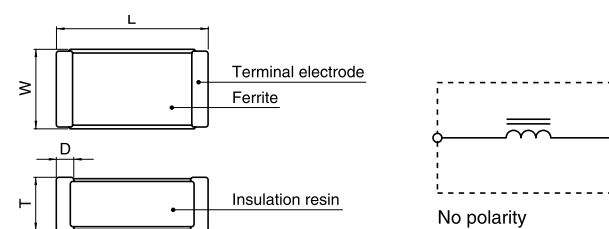
Packaging style	Type	Quantity
Taping	201209	2000 pieces/reel
	321611	2000 pieces/reel
	322513	2000 pieces/reel
	453215	1000 pieces/reel
	575018	500 pieces/reel
	575032	500 pieces/reel
	635050	300 pieces/reel

HANDLING AND PRECAUTIONS

- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and product temperature does not exceed 150°C.
- After mounting components onto the printed circuit board, do not apply stress through board bending or mishandling.
- Do not expose the inductors to stray magnetic fields.
- Avoid static electricity discharge during handling.
- When hand soldering, apply the soldering iron to the printed circuit board only. Temperature of the iron tip should not exceed 350°C. Soldering time should not exceed 3 seconds.



SHAPES AND DIMENSIONS/CIRCUIT DIAGRAM

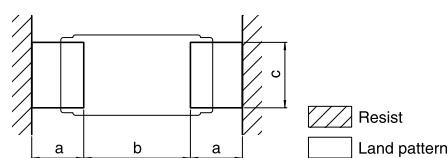


Type	L	W	T	D	Dimensions in mm
201209	2.0±0.2	1.25±0.2	0.9±0.2	0.3±0.2	
321611	3.2±0.2	1.6±0.2	1.1±0.2	0.3±0.2	
322513	3.2±0.2	2.5±0.2	1.3±0.2	0.3±0.2	
453215	4.5±0.25	3.2±0.25	1.5±0.25	0.3±0.2	
575018	5.7±0.4	5.0±0.3	1.8±0.3	0.2	
575032	5.7±0.4	5.0±0.3	3.2±0.3	0.2	
635050	6.4±0.4	5.0±0.3	4.74±0.3	0.2	

• Dimension without tolerance is reference value.

RECOMMENDED PC BOARD PATTERN

REFLOW SOLDERING



Type	a	b	c	Dimensions in mm
201209	1.0	1.0	1.0	
321611	1.1	2.2	1.4	
322513	1.1	2.2	2.3	
453215	1.5	3.0	3.0	
575018	2.0	4.0	5.8	
575032	2.0	4.0	5.8	
635050	2.0	4.5	5.8	

• Conformity to RoHS Directive: This means that, in conformity with EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.

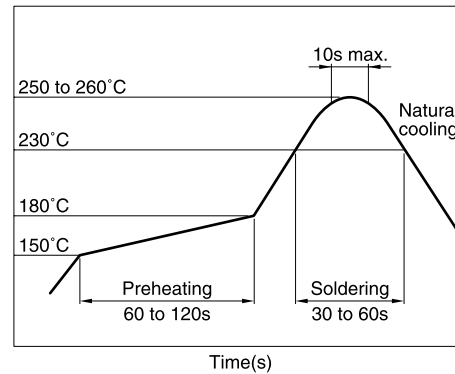
• Please contact our Sales office when your application are considered the following:

The device's failure or malfunction may directly endanger human life (e.g. application for automobile/aircraft/medical/nuclear power devices, etc.)

ELECTRICAL CHARACTERISTICS

Shape	Part No.	Impedance (Ω)[100MHz]	DC resistance (Ω)max.	Rated current (A)max.
201209	HF70ACC201209	10 \pm 25%	0.03	1.5
	HF50ACC201209	11 \pm 25%	0.03	1.5
	HF30ACC201209	7 \pm 25%	0.03	1.5
321611	HF70ACC321611	26 \pm 25%	0.04	1.5
	HF50ACC321611	31 \pm 25%	0.04	1.5
	HF30ACC321611	19 \pm 25%	0.04	1.5
322513	HF70ACC322513	52 \pm 25%	0.05	1.5
	HF50ACC322513	60 \pm 25%	0.05	1.5
	HF30ACC322513	31 \pm 25%	0.05	1.5
453215	HF70ACC453215	120 \pm 25%	0.05	1.5
	HF50ACC453215	125 \pm 25%	0.05	1.5
	HF30ACC453215	70 \pm 25%	0.05	1.5
575018	HF70ACC575018	150 \pm 25%	0.04	3.0
	HF50ACC575018	180 \pm 25%	0.04	3.0
	HF30ACC575018	100 \pm 25%	0.04	3.0
575032	HF70ACC575032	300 \pm 25%	0.04	3.0
	HF50ACC575032	400 \pm 25%	0.04	3.0
	HF30ACC575032	270 \pm 25%	0.04	3.0
635050	HF70ACC635050	500 \pm 25%	0.04	3.0
	HF50ACC635050	600 \pm 25%	0.04	3.0
	HF30ACC635050	750 \pm 25%	0.04	3.0

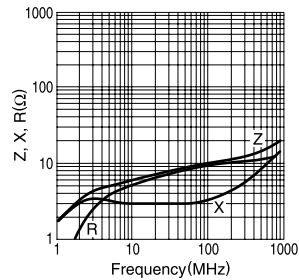
RECOMMENDED SOLDERING CONDITION REFLOW SOLDERING



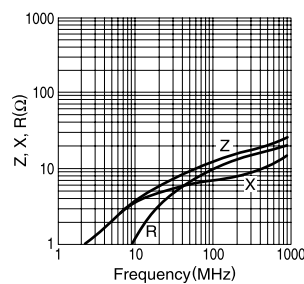
TYPICAL ELECTRICAL CHARACTERISTICS

Z, X, R vs. FREQUENCY CHARACTERISTICS

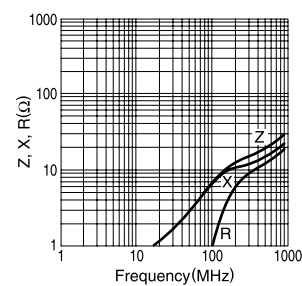
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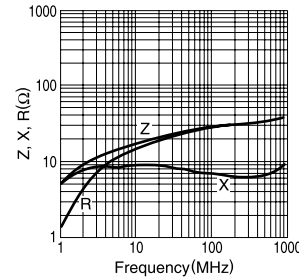
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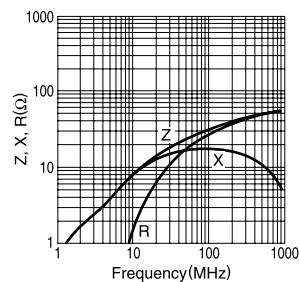
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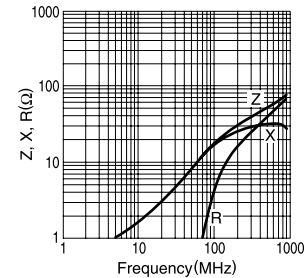
HF70ACC321611



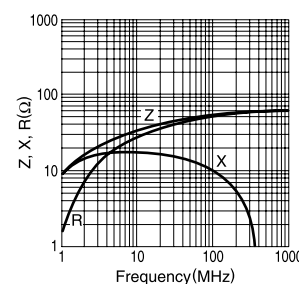
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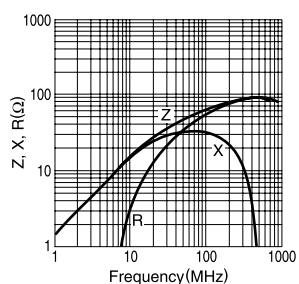
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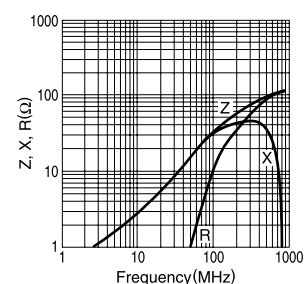
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HF50ACC322513

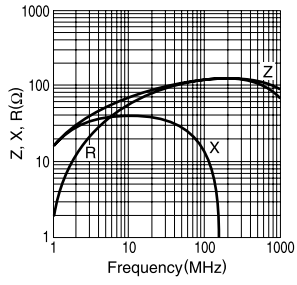


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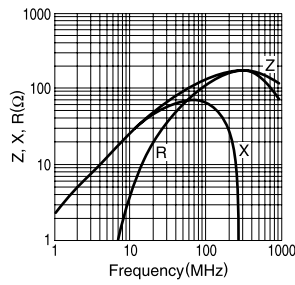


TYPICAL ELECTRICAL CHARACTERISTICS
Z, X, R vs. FREQUENCY CHARACTERISTICS

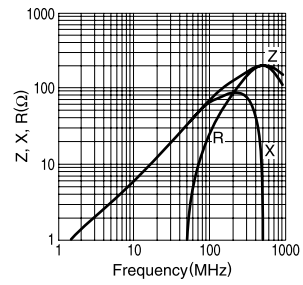
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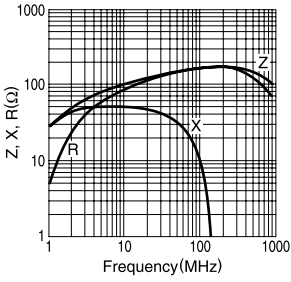
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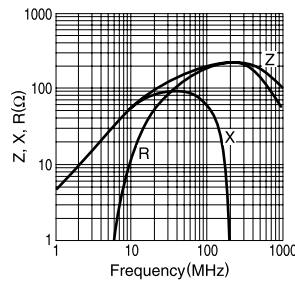
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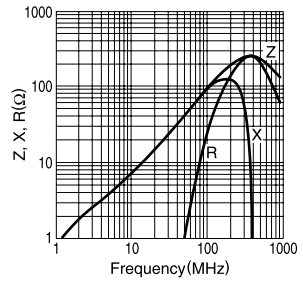
HF70ACC575018



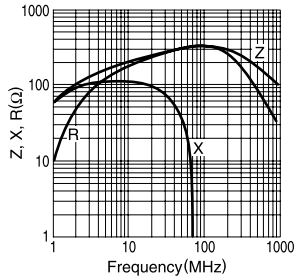
HF50ACC575018



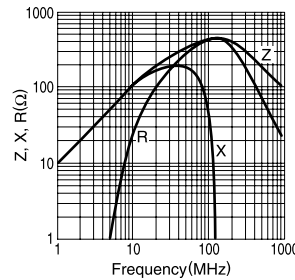
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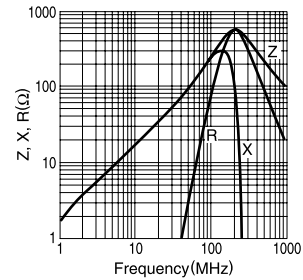
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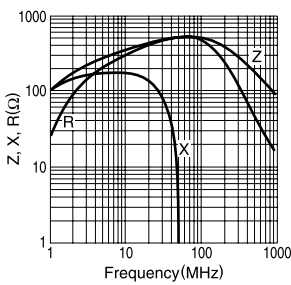
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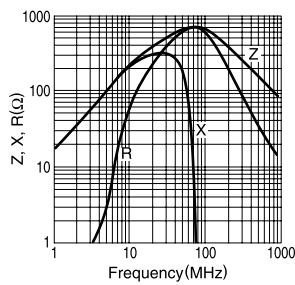
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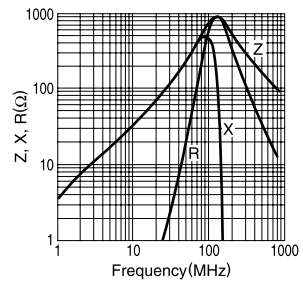
HF70ACC635050



HF50ACC635050



HF30ACC635050



• TEST EQUIPMENT: RF IMPEDANCE ANALYZER YHP4191A